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(57) Abstract :

ABSTRACT TITLE: A system and method to integrate PCM into synthetic jet based heat sink A compact integrated heat sink system with integrated PCM based heat sink assembly (1A) and synthetic jet is provided with unique system configuration with the PCM (phase change material) based heat sink placed directly into the cavity of the synthetic jet thereby solving the problem of optimum distance of the synthetic jet. This makes the heat sink compact, and further the integration of the PCM into the heat sink gives a thermal buffer storage that safeguards the electronic devices against the sudden power surge. The present invention is useful to find end use and application for effective implementation in the field of electronic cooling, and other thermal management applications. Figure 15

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